



UPDATE NOTIFICATION
Generic Copy

06-Apr-2006

SUBJECT: ON Semiconductor Update Notification #15505

TITLE: Update to 15339: Initial notice of intent to qualify Hana Semiconductor for Micro08, Micro10, and TSOP5 capacity expansion

EFFECTIVE DATE: 30-Jul-2006

AFFECTED CHANGE CATEGORY: Subcontractor Assembly & Test Site

AFFECTED PRODUCT DIVISION: Analog Power Management

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact Sales Office or Shannon Riggs <r13350@onsemi.com>

NOTIFICATION TYPE:

Initial Product/Process Change Notification (IPCEN)

First change notification sent to customers. IPCENs are issued at least 120 days prior to implementation of the change. An IPCEN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCEN).

This IPCEN notification will be followed by a Final Product/Process Change Notification (FPCEN) at least 60 days prior to implementation of the change.

DESCRIPTION AND PURPOSE:

***** Update to 15339 *****

The decision has been made to remove the TSOP5 package from the Hana move except for the NCP345 family. An automotive NCP345 standard, (NCV345SNT1G) has been set up for automotive customers requiring this device family. Hana Semiconductor will not be utilized for automotive applications.

This is an Initial Product Change Notice to make customers aware that Hana Semiconductor (HANA), located in Ayutthaya, Thailand is being qualified as a supplemental assembly source for ON Semiconductor's Analog Micro08, Micro10, and TSOP5 products. Hana is a fully certified ISO9002 and QS9000 supplier. These packages are currently manufactured in ON Semiconductor's facility in Seremban, Malaysia. This is not a transfer but a capacity expansion. Device parameters will continue to meet all Data Book specifications, and reliability will continue to meet or exceed ON Semiconductor standards. Upon expiration of the FINAL PCN(s), the affected devices may be processed at either location depending on capacity requirements.

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FINAL PCN(s) will be issued as needed to accommodate the varying qualification schedules for the affected devices. Samples will be available once the FINAL PCN(s) is(are) published.

QUALIFICATION PLAN:

AC/PC 121C, 15psig, 100%RH 96hrs
 TC/PC -65/150C 500cycles
 HTSL 150C 504hrs
 Solderability 245C, 8hrs
 Solder Heat 260C, 10sec
 Solder Heat 310C, 10sec
 HAST/PC 130C, 85%RH 96hrs
 HTOL 150C 504hrs

Testing will be adjusted, as required, to ensure appropriate qualification coverage for the largest die size in the package.

AFFECTED DEVICE LIST:

Device	Devices	Devices	Devices
LM258DMR2	LP2951CDMR2	MC34064DM-5R2G	NCP1530DM30R2G
LM258DMR2G	LP2951CDMR2G	MC34161DMR2	NCP1530DM33R2
LM2903DMR2	MAX707CUA-T	MC34161DMR2G	NCP1530DM33R2G
LM2903DMR2G	MAX707CUA-TG	MC34164DM-3R2	NCP1800DM41R2
LM2904ADMG	MAX708CUA-T	MC34164DM-3R2G	NCP1800DM41R2G
LM2904ADMR2	MAX708CUA-TG	MC34164DM-5R2	NCP1800DM42R2
LM2904ADMR2G	MAX708RCUA-T	MC34164DM-5R2G	NCP1800DM42R2G
LM2904DMR2	MAX708RCUA-TG	NB4N855SMR4	NCP2809ADMR2
LM2904DMR2G	MAX708SCUA-T	NB4N855SMR4G	NCP2809ADMR2G
LM2904VDMR2	MAX708SCUA-TG	NCP1030DMR2	NCP2809BDMR2
LM2904VDMR2G	MAX708TCUA-T	NCP1030DMR2G	NCP2809BDMR2G
LM293DMR2	MAX708TCUA-TG	NCP1410DMR2	NCP2860DM277R2
LM293DMR2G	MC1455BDMR2	NCP1410DMR2G	NCP2860DM277R2G
LM358DMR2	MC1455DMR2	NCP1411DMR2	NCP2890DMR2
LM358DMR2G	MC33064DM-5R2	NCP1411DMR2G	NCP2890DMR2G
LM393DMR2	MC33064DM-5R2G	NCP1417DMR2	NCP3335ADM250R2G
LM393DMR2G	MC33161DMR2	NCP1421DMR2	NCP3335ADM285R2G
LP2951ACDM-3.0R2	MC33161DMR2G	NCP1421DMR2G	NCP3335ADM330R2G
LP2951ACDM-3.3R2	MC33164DM-3R2	NCP1423DMR2	NCP3335ADM500R2G
LP2951ACDM-3.3RG	MC33164DM-3R2G	NCP1423DMR2G	NCP3335ADMADJR2G
LP2951ACDM-5.0R2	MC33164DM-5R2	NCP1500DMR2	NCP3335DMR2250G
LP2951ACDMR2	MC33164DM-5R2G	NCP1500DMR2G	NCP3335DMR2285G
LP2951ACDMR2G	MC33178DMR2	NCP1501DMR2	NCP3335DMR2330G
LP2951CDM-3.0G	MC33178DMR2G	NCP1501DMR2G	NCP345SNT1
LP2951CDM-3.0R2	MC33202DMR2	NCP1530DM25R2	NCP345SNT1G
LP2951CDM-3.0R2G	MC33202DMR2G	NCP1530DM25R2G	NCP4894DMR2
LP2951CDM-3.3G	MC33565DMR2	NCP1530DM27R2	NCP4894DMR2G
LP2951CDM-3.3R2	MC33565DMR2G	NCP1530DM27R2G	NCP5008DMR2
LP2951CDM-3.3R2G	MC34064DM-5R2	NCP1530DM30R2	NCP5008DMR2G



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AFFECTED DEVICE LIST con't:

Devices

- NCP623DM-33R2
- NCP623DM-33R2G
- NCP623DM-40R2
- NCP623DM-40R2G
- NCP623DM-50R2
- NCP623DM-50R2G
- NLAS4684MR2
- NLAS4684MR2G
- NLAS4685MR2
- NLAS4685MR2G
- NLAS4717EPMR2G
- NLAS4717MR2
- NLAS4717MR2G
- NTTS2P02R2G
- PB4N855SMR4G
- TL431ACDMR2
- TL431ACDMR2G
- TL431AIDMR2
- TL431AIDMR2G
- TL431BCDMR2
- TL431BCDMR2G
- TL431BIDMR2
- TL431BIDMR2G
- TL431BVDMR2
- TL431BVDMR2G
- TL431CDMR2
- TL431CDMR2G
- TL431IDMR2
- TL431IDMR2G